



IPC J-STD-030A

Selection and Application of Board Level Underfill Materials

Developed by the Underfill Materials Design, Selection and Process Task Group (5-24f) of the Assembly and Joining Committee (5-20) of IPC

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Users of this publication are encouraged to participate in the development of future revisions.

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Table of Contents

1 SCOPE	1	7.2	Storage Conditions	10
1.1 Introduction	1	7.3	Preconditioning	11
1.2 Purpose	1	7.4	Pot Life	11
1.3 Definition of Requirements	1	7.4.1	Viscosity Change	11
2 APPLICABLE DOCUMENTS	2	7.4.2	Flow Rate Change	11
2.1 IPC	2	7.4.3	Settling Test	11
2.2 American Society for Testing and Materials (ASTM)	2	8 APPLICATION PROCESS		11
2.3 Telcordia Technologies, Inc.	2	8.1	Pre-Application Board Preparation	12
3 TERMS AND DEFINITIONS	2	8.2	Application of Capillary Flow Underfill	12
4 BACKGROUND	3	8.2.1	Dispensing Procedures	13
4.1 Why Is Underfill Needed?	3	8.2.1.1	Dispensing Patterns	13
4.2 Types of Underfill	4	8.2.1.2	Process Parameters	14
4.2.1 Capillary Underfill	4	8.2.2	Application Problems	14
4.2.2 Fluxing (No-Flow) Encapsulant	4	8.2.2.1	Air Entrapment	14
4.2.3 Removable/Reworkable Underfill	5	8.2.2.2	Gravitational Phase Separation	14
4.2.4 Cornerbond Adhesive (Dispensed or Placed Prior to Reflow Process)	5	8.2.2.3	Dynamic Phase Separation	15
4.2.5 Corner Glue/Corner Tack Underfills (Applied After SMT Reflow)	5	8.2.2.4	Filtering Phase Separation	15
5 MECHANICAL CONSIDERATIONS	6	8.3	Application of No-Flow/Fluxing Underfill	15
5.1 Footprint Design	6	8.3.1	Dispensing Pattern	15
5.2 Gap Size	7	8.3.2	Dispense Volume	15
5.3 Pad Redistribution	7	8.3.3	Package Placement	15
6 UNCURED UNDERFILL CHARACTERISTICS	7	8.3.4	Application Problems	16
6.1 Filler Properties	7	8.4	Flow Rate	16
6.1.1 Filler Size	7	8.4.1	Dispense Flow Rate Measurement	16
6.1.2 Filler Material Type	8	8.4.2	Underfill Flow Rate	16
6.1.3 Filler Content	8	8.4.3	Flow Out and Bleed	16
6.1.4 Density	8	8.5	Spread/Slump	17
6.2 Prepolymer Properties	8	8.6	Evaluation Methodology	17
6.2.1 Viscosity	8	8.6.1	Acoustic Micro-Imaging	17
6.2.2 Gel Time	8	8.6.2	Destructive Tests for Voiding	17
6.3 Material Compatibility	8	8.6.3	Assembly to Glass for Flow Visualization	18
6.3.1 Flux Compatibility	8	8.7	Pot Life (In Dispenser)	18
6.3.2 Board Surface Compatibility	9	9 CURE PROCESS		18
6.3.3 Component Surface Compatibility	9	9.1	Applied Life (After Dispensing)	18
6.4 Alpha Particle Emissions	9	9.2	Cure Process for Capillary Flow Underfill	19
7 MATERIALS PACKAGING, HANDLING, AND STORAGE	10	9.2.1	Process Parameters	19
7.1 Packaging and Containers	10	9.2.2	Cure Schedule	19
7.1.1 Voids/Bubbles in Packed Material	10	9.2.3	Heating Rate	19
		9.2.4	Temperature Sensitivity	19
		9.3	Cure Process for No-Flow Underfill	19
		9.4	Void Formation/Outgassing	20
		9.5	Cure Verification	20

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Figure 8-7	Dynamic Phase Separation	15
Figure 8-8	Filtering Phase Separation	15
Figure 8-9	Underfill Bleed	17
Figure 9-1	Filler Settling within Underfill	18
Figure 10-1	Underfill Adhesion Test	21
Figure 12-1	Material Property and Thermal Cycling Response	25
Figure 13-1	Acceptable – Class 1,2,3	27
Figure 13-2	Void Comparison	28
Figure 13-3	Target – Flat Cross Section that Shows No Voids in the Underfill Layer	29
Figure 13-4	Image of a Component with Edgebond Underfill	29
Figure 13-5	Fillet Width	29
Figure 14-1	Filtering Phase Separation	30

Tables

Table 4-1	Guidelines for Evaluation	4
Table 8-1	Test Methods	18
Table 10-1	Conditions for Chemical Resistance Testing	22

Selection and Application of Board Level Underfill Materials

1 SCOPE

This document provides users of underfill material with guidance in selecting and evaluating underfill material for assembly solder joints second level interconnects. Underfill material is used to increase reliability of electronic devices by two methods: alleviate coefficient of thermal expansion (CTE) mismatch (between the electronic package and the assembly substrate) and/or increase mechanical strength. Underfill materials are also used for environmental protection, mechanical shock or vibration, and anti-tampering uses. Materials used in underfill applications should not adversely affect device reliability nor degrade electrical performance (e.g., ionic impurities). When correctly selected and applied, underfill material should increase the life of the assembly solder joints.

Types of underfill materials currently available in the market include:

- Capillary Flow Underfill
 - Primary UFs (Package level not within the scope of this document)
 - Secondary (Board level)
- No-Flow/Fluxing Underfill
 - Thermal Compression Bonding (TCB) Epoxies (not within the scope of this document)
 - Non-Conductive Paste (NCP)
 - Non-Conductive Film (NCF)
- Removable/Re-Workable Underfill
- Corner Bonding/Glue Bonding
- Molded Underfill (not within scope of document)
- Wafer Applied Underfill (not within scope of document)
- Vacuum Underfill (not within scope of document)

1.1 Introduction This document covers polymer based underfill materials intended for use in printed circuit assemblies (PCA). (See Figure 1-1.)

1.2 Purpose The purpose of this document is to help in identifying underfill materials whose properties are compatible with component assembly joints to reduce thermo mechanical stress so that performance of the assembly is enhanced. The additional role of underfill is protecting the device from environmental factors and increasing strength. Evaluation methods are provided in the document that are intended to be used for assessing underfill material performance in specific applications as well as troubleshooting failures. This document represents the compiled knowledge and experience of the IPC Underfill Adhesives for Flip Chip Applications Task Group.

1.3 Definition of Requirements The word “shall” is used in the text of this document wherever there is a requirement for materials, preparation, process control, or acceptance of a soldered connection or a test method. The word “should” reflects “best processing techniques” and is used to reflect general industry practices and a suggestion for guidance only.

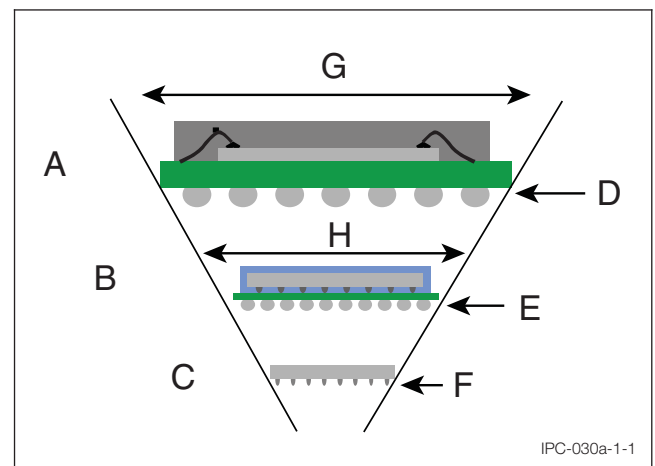


Figure 1-1 Comparison of Various Sized Array Packages

- | | |
|-----------------------------|---------------------|
| A. Ball Grid Array (BGA) | E. 300 micron balls |
| B. Chip Scale Package (CSP) | F. 75 micron balls |
| C. Flip Chip (FP) | G. 35 mm [1.38 in] |
| D. 760 micron balls | H. 1.2x chip size |